



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPI200N25N3 G	Issued	17. February 2022
MA#	MA005698381		
Package	PG-TO262-3-1	Weight*	1584.69 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.562	1.11	1.11	11083	11083
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		161	
	non noble metal	iron	7439-89-6	0.851	0.05		537	
	non noble metal	copper	7440-50-8	849.682	53.62	53.69	536180	536878
wire	non noble metal	aluminium	7429-90-5	14.639	0.92	0.92	9238	9238
encapsulation	inorganic material	zinc oxide	1314-13-2	5.696	0.36		3595	
	miscellaneous	miscellaneous	-	22.785	1.44		14378	
	plastics	epoxy resin	-	85.444	5.39		53918	
	inorganic material	silicon dioxide	60676-86-0	455.700	28.76	35.95	287564	359455
lead finish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9590	9590
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	144	145
solder	non noble metal	tin	7440-31-5	0.206	0.01		130	
	noble metal	silver	7440-22-4	0.258	0.02		163	
	non noble metal	lead	7439-92-1	9.839	0.62	0.65	6209	6502
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			20	
	non noble metal	iron	7439-89-6	0.106	0.01		67	
	non noble metal	copper	7440-50-8	106.210	6.70	6.71	67022	67109
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com